

# **60V N-Channel MOSFET**

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX.	I <sub>D</sub>	
60V	20mΩ	50A	

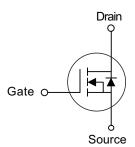
#### **Feature**

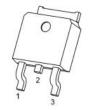
- Lower R<sub>DS(ON)</sub> to Minimize Conduction Losses
- 60V,50A,  $R_{DS(ON)}Max. = 20m\Omega@V_{GS} = 10V$
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

## **Application**

- Portable Equipment and Battery Powered systems.
- Power Management in Notebook Computer

## Symbol





TO-252(G:1 D:2 S:3)

### Absolute maximum ratings (Ta=25°C?unless otherwise noted)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{DSS}$	60	V
Gate-Source Voltage		$V_{GSS}$	±20	V
Drain Current	Continuous	I <sub>D</sub>	50	Α
	Pulsed (Note 2)	$I_{DM}$	100	Α
Avalanche Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	66	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	6.4	V/ns
Power Dissipation		$P_D$	28	W
Junction Temperature		$T_J$	+150	°C
Storage Temperature Range		T <sub>STG</sub>	-55 ~ <b>+</b> 150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L = 0.1 mH,  $I_{AS}$  = 25A,  $V_{DD}$  = 25V,  $R_G$  = 25 $\Omega$ , Starting  $T_J$  = 25°C.
- 4.  $I_{SD} \le 30 A$ ,  $di/dt \le 200 A/\mu s$ ,  $V_{DD} \le V_{(BR)DSS}$ ,  $T_J = 25 ^{\circ} C$ .

#### THERMAL CHARACTERISTICS

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	$\theta_{JA}$	65 (Note)	°C/W
Junction to Case	$\theta_{JC}$	4.46 (Note)	°C/W

Note: The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.



# Electrical characteristics (T<sub>A</sub>=25 °C, unless otherwise noted)

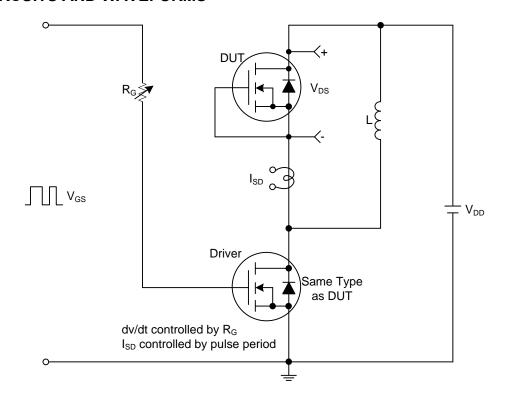
DADAMETER		SYMBOL	TEST CONDITIONS	MIN	TVD	MAX	LINIT
PARAMETER		STIVIDUL	TEST CONDITIONS	IVIIIN	וור	IVIAA	UIVII
Off characteristics		D\/	L -250uA \/ -0\/	60			V
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	60		4.0	
Drain-Source Leakage Current		I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V			1.0	μA
Gate-Source Leakage Current	orward	$I_{GSS}$	V <sub>GS</sub> =+20V, V <sub>DS</sub> =0V			+100	nA
JR:	everse		V <sub>GS</sub> =-20V, V <sub>DS</sub> =0V			-100	nA
On characteristics			1		1	1	
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	1.0		3.0	V
Static Drain-Source On-State Resista	ance	В	$V_{GS}=10V$ , $I_D=25A$		16	20	mΩ
Static Drain-Source On-State Resista	ance	R <sub>DS(ON)</sub>	$V_{GS}$ =4.5V, $I_D$ =20A		20	24	mΩ
Dynamic characteristics							
Input Capacitance		C <sub>ISS</sub>			1820		pF
Output Capacitance Reverse Transfer Capacitance		Coss	$V_{GS}$ =0V, $V_{DS}$ =25V, f=1.0MHz		220		pF
		$C_{RSS}$			180		pF
Switching characteristics							
Total Gate Charge (Note 1)		$Q_G$	-\/ -48\/ \/ -10\/   -50^		62		nC
Gate to Source Charge		$Q_GS$	V <sub>DS</sub> =48V, V <sub>GS</sub> =10V, I <sub>D</sub> =50A, I <sub>G</sub> =100μA (Note 1, 2)		7		nC
Gate to Drain Charge		$Q_GD$	IG-100μΑ (Note 1, 2)		18		nC
Turn-on Delay Time (Note 1)		$t_{D(ON)}$			8		ns
Rise Time		t <sub>R</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =50A,		18		ns
Turn-off Delay Time	Turn-off Delay Time		R <sub>G</sub> =3Ω (Note 1, 2)		44		ns
Fall-Time		t <sub>F</sub>			22		ns
Source-drain diode ratings characteristics							
Maximum Body-Diode Continuous Current		Is				50	Α
Maximum Body-Diode Pulsed Current		I <sub>SM</sub>				100	Α
Drain-Source Diode Forward Voltage (Note 1)		$V_{SD}$	I <sub>S</sub> =50A, V <sub>GS</sub> =0V			1.3	V
Reverse Recovery Time (Note 1)		t <sub>rr</sub>	I <sub>S</sub> =30A, V <sub>GS</sub> =0V,		102		nS
Reverse Recovery Charge		$Q_{rr}$	dI <sub>F</sub> /dt =100A/μs		140		nC

Notes: 1. Pulse Test : Pulse width  $\leq$  300 $\mu$ s, Duty cycle  $\leq$  2%.

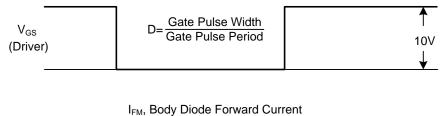
<sup>2.</sup> Essentially independent of operating ambient temperature.



### **TEST CIRCUITS AND WAVEFORMS**

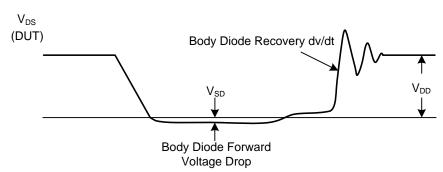


#### Peak Diode Recovery dv/dt Test Circuit



I<sub>SD</sub> (DUT) di/dt

Body Diode Reverse Current

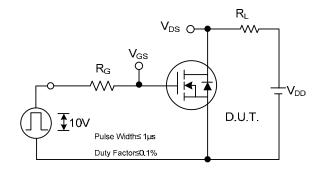


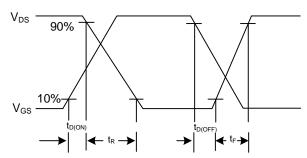
Peak Diode Recovery dv/dt Test Circuit and Waveforms

### Peak Diode Recovery dv/dt Waveforms



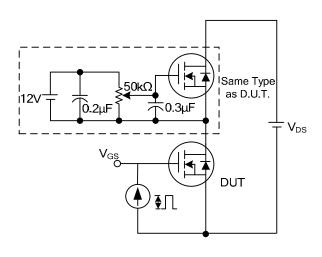
### **TEST CIRCUITS AND WAVEFORMS(Cont.)**

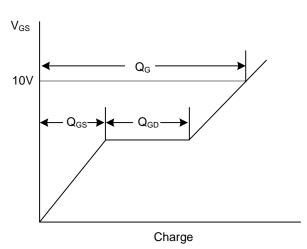




**Switching Test Circuit** 

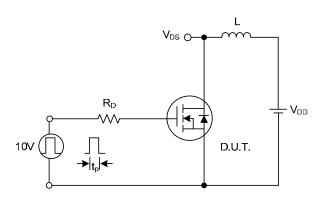
**Switching Waveforms** 

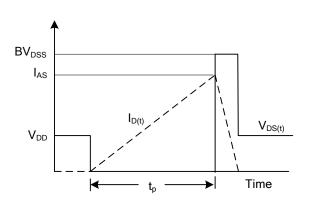




**Gate Charge Test Circuit** 

**Gate Charge Waveform** 



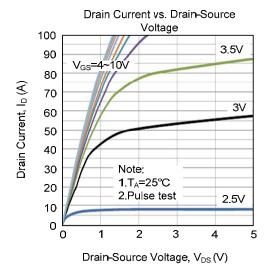


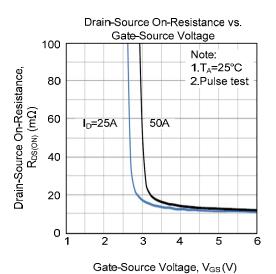
**Unclamped Inductive Switching Test Circuit** 

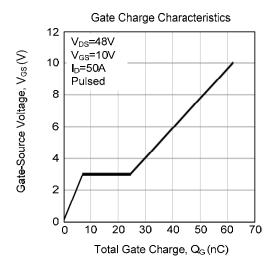
**Unclamped Inductive Switching Waveforms** 

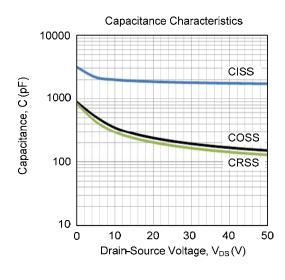


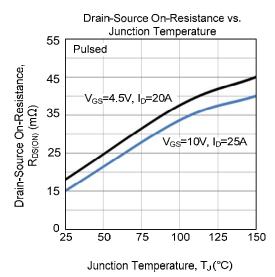
#### TYPICAL CHARACTERISTICS

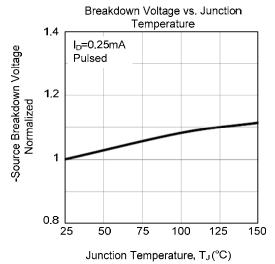






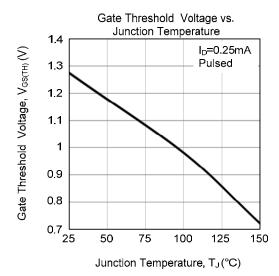


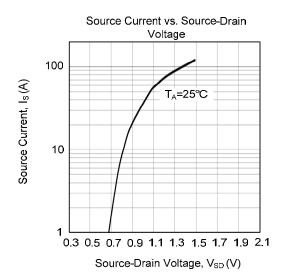


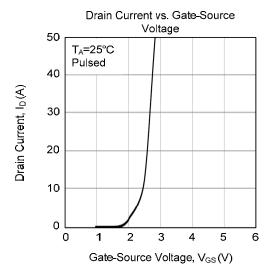


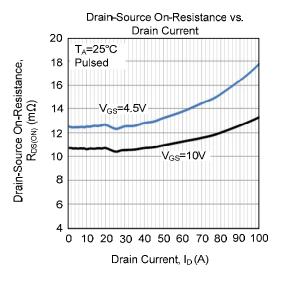


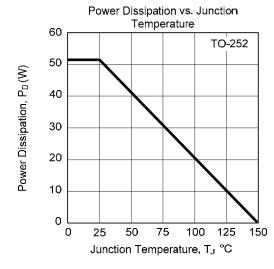
### **TYPICAL CHARACTERISTICS(Cont.)**

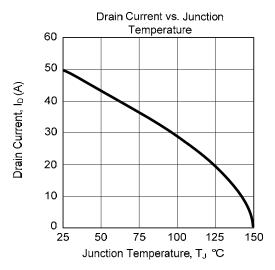






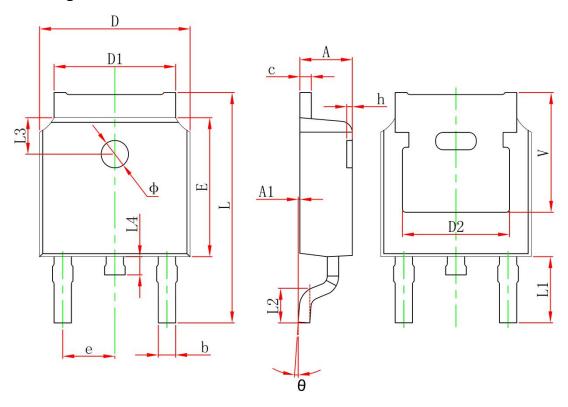








# **TO-252 Package Mechanical Data**



	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 REF.		0.190 REF.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 REF.		0.114 REF.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 REF.		0.063 REF.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 REF. 0.211 R		EF.		